

**PARTICLE DISPERSIONS****Patent number:** WO0132799**Publication date:** 2001-05-10**Inventor:** REITZ HARIKLIA DRIS; BI XIANGXIN; KAMBE NOBUYUKI; KUMAR SUJEET**Applicant:** NANOGRAM CORP (US)**Classification:**

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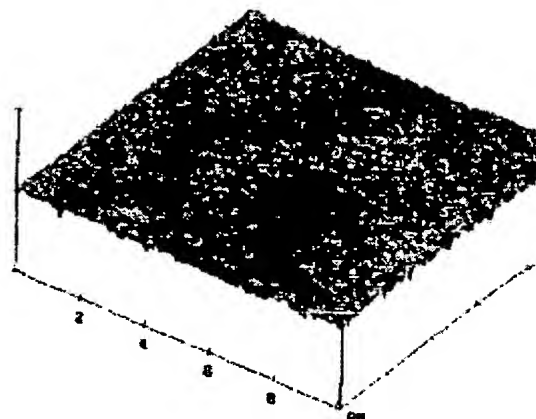
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US53  
US58  
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**Abstract of WO0132799**

Improved particle dispersions are formed using nanoparticles with average primary particle diameters less than about 100 nm. The collection of nanoparticles in the dispersion have very narrow particles size distributions that do not have tails at larger particle sizes. In particular, the collection of nanoparticles effectively do not have primary particles with a diameter greater than three times the average particle diameter. The improved dispersions can be used in the formation of polishing compositions for chemical-mechanical polishing and in the production of thin coatings.



**RMS: 0.46 nm**  
**R<sub>max</sub>: 5.76 nm**

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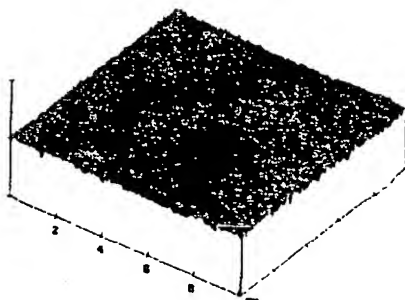
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(54) Title: PARTICLE DISPERSIONS



(57) Abstract: Improved particle dispersions are formed using nanopar-  
ticles with average primary particle diameters less than about 100 nm.  
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